muRata

Reference Specification

DEB Series Lead Type Disc Ceramic Capacitors of Class 2 for General Purpose

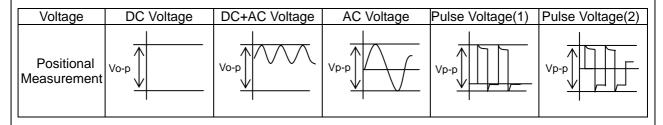
Product specifications in this catalog are as of Dec. 2017, and are subject to change or obsolescence without notice.

Please consult the approval sheet before ordering. Please read rating and Cautions first.

1. OPERATING VOLTAGE

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range. When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing these irregular voltage.

When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for each equipment should be taken into considerations.



2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

When the capacitor is used in a high-frequency current, pulse current or the like, it may have the selfgenerated heat due to dielectric-loss. The allowable frequency should be in less than 300kHz in sine wave. Applied voltage should be the load such as self-generated heat is within 20 °C <u>on the condition of</u> <u>atmosphere temperature 25 °C.</u> When measuring, use a thermocouple of small thermal capacity-K of ϕ 0.1mm and be in the condition where capacitor is not affected by radiant heat of other components and wind of surroundings. While, in case of non-sine wave which include a harmonic frequency, please contact our sales representatives or product engineers.

3. FAIL-SAFE

When capacitor would be broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

4. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

5. SOLDERING

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron tip : 400 °C max.

Soldering iron wattage : 50W max.

Soldering time : 3.5 s max.

6. BONDING, RESIN MOLDING AND COATING

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive, molding resin or coating may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

7. TREATMENT AFTER BONDING, RESIN MOLDING AND COATING

When the outer coating is hot (over 100 $^{\circ}$ C) after soldering, it becomes soft and fragile. So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

8. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors

in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 °C and 15 to 85%. Use capacitors within 6 months after delivered. Check the solderability after 6 months or more.

9. LIMITATION OF APPLICATIONS

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. Power plant control equipment
- 5. Medical equipment
- 6. Transportation equipment (vehicles, trains, ships, etc.)
- 7. Traffic signal equipment
- 8. Disaster prevention / crime prevention equipment
- 9. Data-processing equipment exerting influence on public
- 10. Application of similar complexity and/or reliability requirements to the applications listed in the above.

NOTICE

1. CLEANING (ULTRASONIC CLEANING)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity : Output of 20 watts per liter or less.

Rinsing time : 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. CAPACITANCE CHANGE OF CAPACITORS

- Class 1 capacitors

Capacitance might change a little depending on a surrounding temperature or an applied voltage. Please contact us if you use for the strict time constant circuit.

- Class 2 and 3 capacitors

Class 2 and 3 capacitors like temperature characteristic B, E and F have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor leaves for a long time. Moreover, capacitance might change greatly depending on a surrounding temperature or an applied voltage. So, it is not likely to be able to use for the time constant circuit. Please contact us if you need a detail information.

- 1.Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- 2. You are requested not to use our product deviating from this specification.

Γ

Class 2 of DEI Do not use the for electric veh	B series used f se products in	or Genera any autor	al Electric equinotive powe				ratings and battery chargers
2. Rating 2-1. Operating -25							
2-2. Part numb	er configuratio	n					
ex.) <u>DEB</u> Series	<u>B3</u> Temperature characteristic	<u>3D</u> Rated voltage	<u>332</u> Capacitanc	e Capacitance tolerance	<u>A3</u> Lead code	B Packing style code	Individual specification
•Temper	rature characte	eristic					
		ode	Ter	nperature chara	cteristic		
		33		<u> </u>			
		<u>=3</u> =3		<u> </u>			
		-	enecification	on [Specificatio	n and to	et methode	1
		laetalleu	specification			St methous].
Rated	voltage						
• Nateu		ode		Rated voltag	Ie.		
		3D		DC2kV	0		
		3F		DC3.15kV			
ex.	e first two digits) In case of 33 33	2. ×10 ² = 33	0 0	ires ; the last diç	git denot	es the multip	blier of 10 in pF.
-	itance toleranc ase refer to [F		er list].				
• Lead c			[
		ode	Vort	Lead style			
		4* C*		al crimp long ty	Je		
		<u>_*</u> 3*		ht long type al crimp short ty	/ne		
		<u>⊃∗</u>)∗		the short type			
		V*		al crimp taping	vpe		
		⊃ _*		taping type	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		
	* Please refer	to [Part					
Sol	der coated cop	oper wire i	s applied for	termination.			

Packing style code

Code	Packing type
В	Bulk type
A	Ammo pack taping type

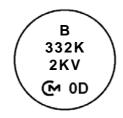
• Individual specification

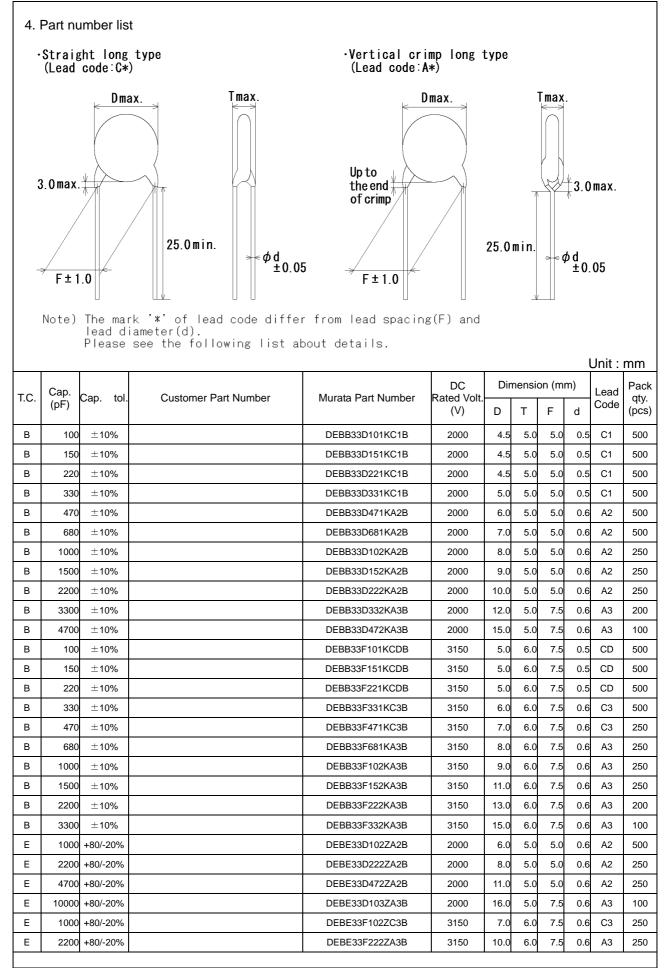
In case part number cannot be identified without 'individual specification', it is added at the end of part number.

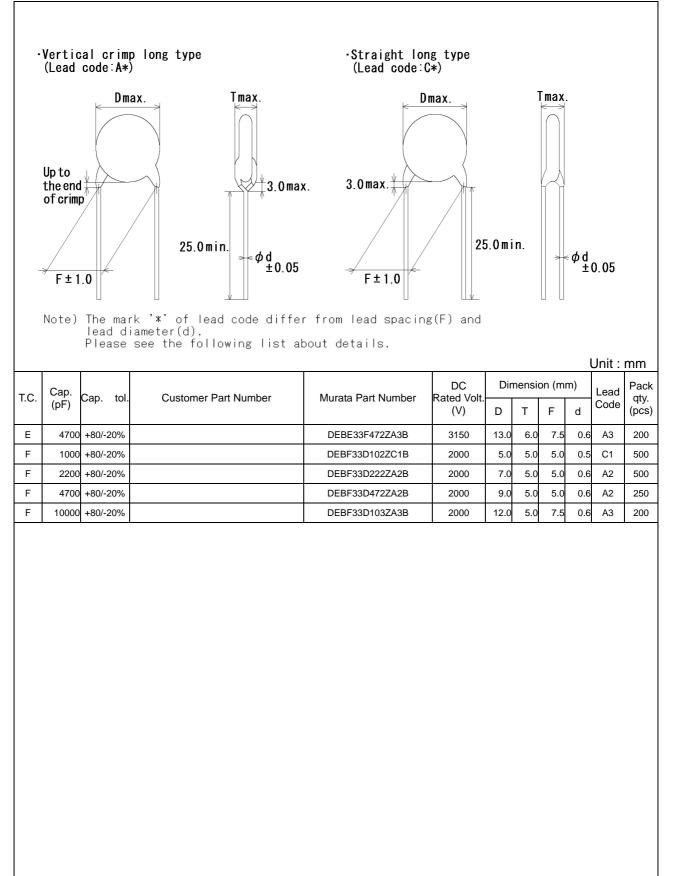
3. Marking

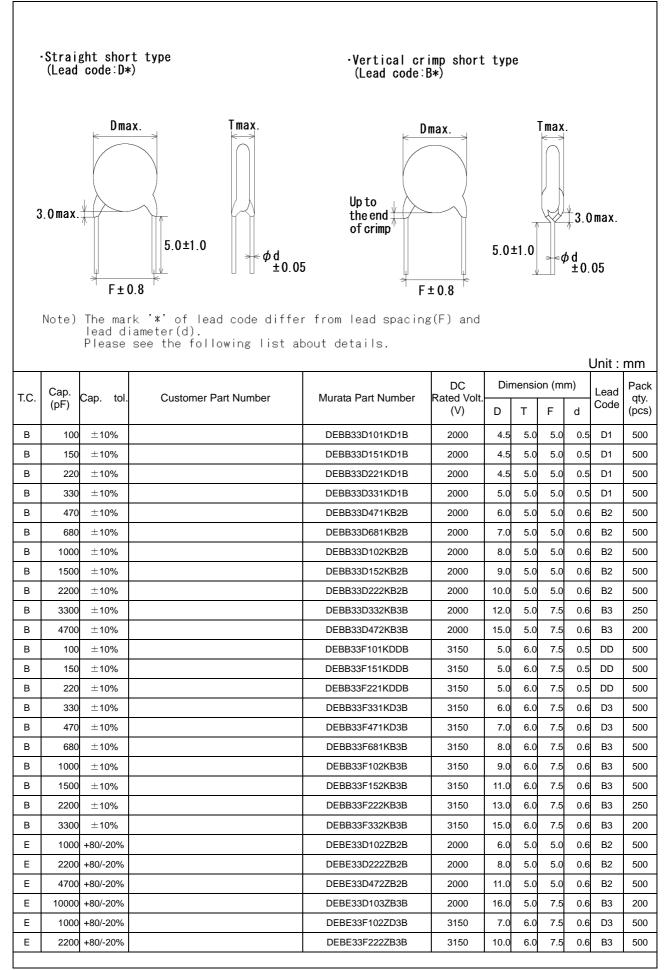
Temperature characteristic	Letter code Identified by code for char. B or char. E.
	(Omitted for maximum body diameter ϕ 9mm and under)
Nominal capacitance	: 3 digit system
Capacitance tolerance	: Code(Omitted for maximum body diameter ϕ 6mm and under)
Rated voltage	: Letter code(In case of DC3.15kV, marked with 3KV)
Company name code	: Abbreviation 🕞
	(Omitted for maximum body diameter ϕ 9mm and under)
Manufacturing year	: Letter code(The last digit of A.D. year.)
	(Omitted for maximum body diameter ϕ 5mm and under)
Manufacturing month	: Code(Omitted for maximum body diameter ϕ 5mm and under) (Feb./Mar. $\rightarrow 2$ Aug./Sep. $\rightarrow 8$ Apr./May $\rightarrow 4$ Oct./Nov. $\rightarrow 0$ Jun./Jul. $\rightarrow 6$ Dec./Jan. $\rightarrow D$

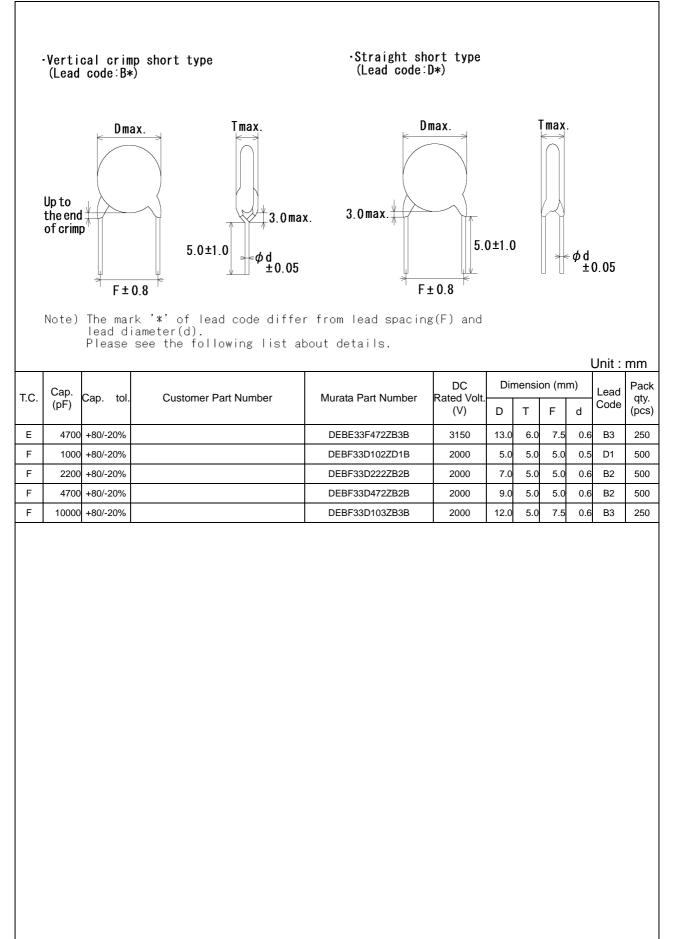
(Example)

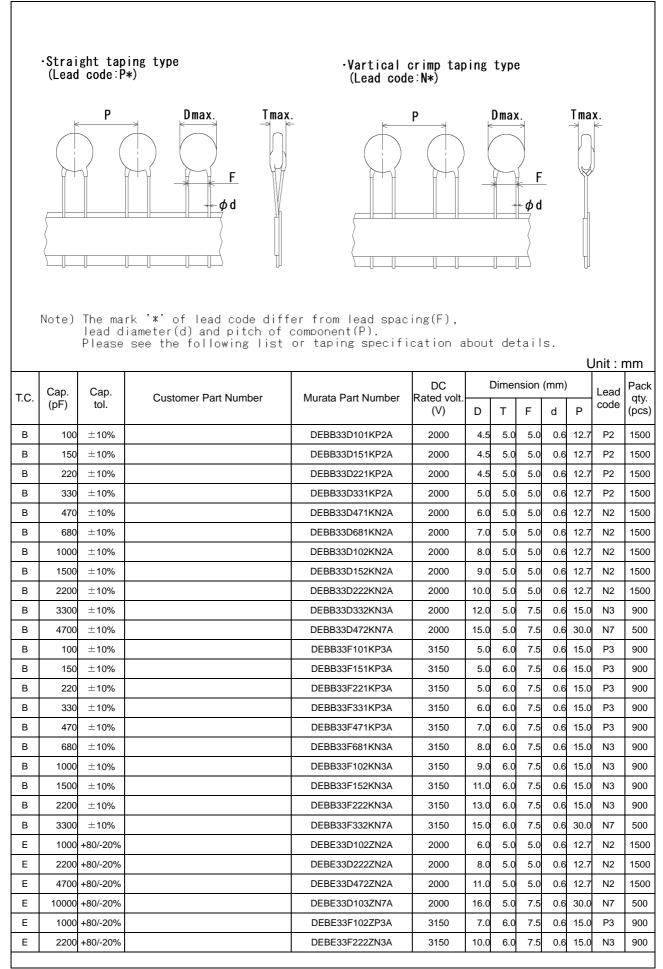


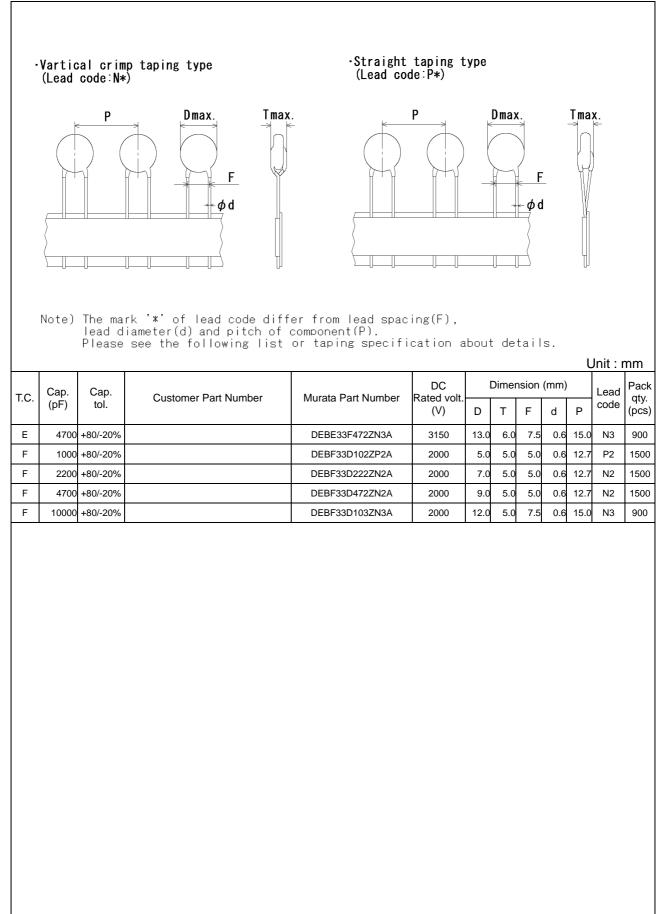












Reference only

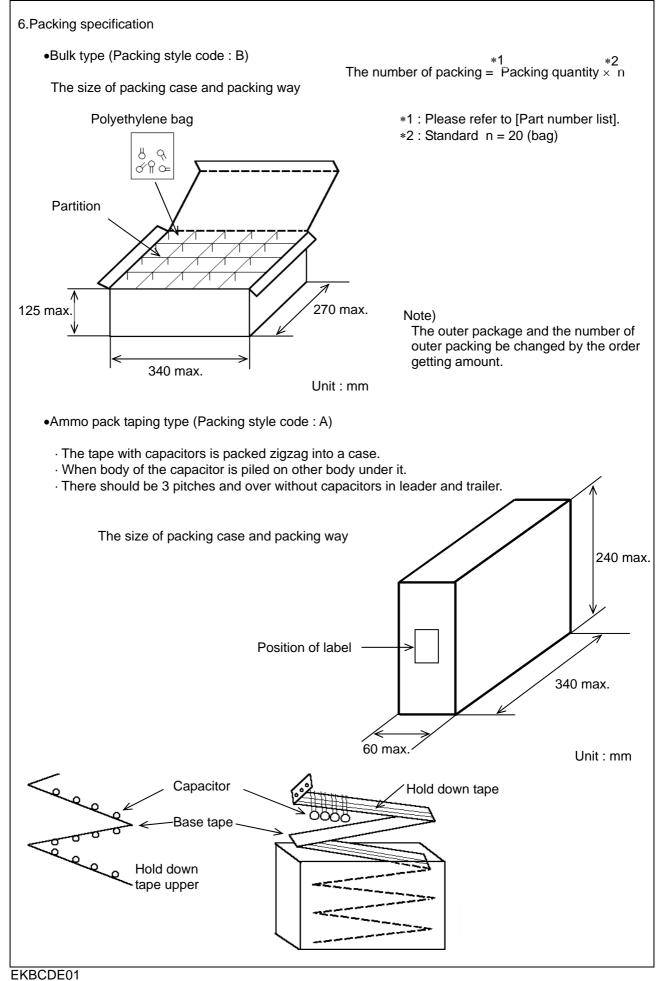
				lefence only					
	ecification and test		-	· · ·			. .		
No.	lte			ification	e The capacitor should be inspected by naked eyes				
1	Appearance and o	dimensions		ect on appearance					naked eyes
			form and dimen				ce of defeo		
				[Part number list].					slide caliper
2	Marking		To be easily leg	ible.	The capacitor should be inspected by na				
3	Dielectric	Between lead	No failure.						d when DC
	strength	wires							are applied
							wires for '		
					(Charge	/Discharg	je current⊴	≦50mA.)	
		Body	No failure.						er with metal
		insulation					1mm so th		ead wire,
							kept about	2mm	
						alls as sh			\vee
						ure, and			Ű.
						of 1.3kV i			A .t.
						for 1 to 5		000	About
						capacito		୍କୁ	
					wires and sma			8	Metal bal
							je current⊴		
4	Insulation	Between lead	$10000M\Omega$ min.		The insulation resistance should be measured			neasured with	
	Resistance (I.R.)	wires			DC500±	50V withi	n 60±5 s d	of charging	g.
5	Capacitance		Within specified	l tolerance.	The cap	acitance	should be	measured	at 20°C with
					1±0.2kHz and AC5V(r.m.s.) max				
6	Dissipation Factor	r (D.F.)	Char. B,E : 2.5%		The dissipation factor should be measured at			sured at 20°C	
	-		Char. F : 5.0%	% max.	with 1±0.2kHz and AC5V(r.m.s.) max				
7	Temperature char	acteristic	Char. B : Within	±10%	The capacitance measurement should be ma			d be made at	
			Char. E : Within		each step specified in Table.				
			Char. F : Within						
		Pre-treatment : Capacitor should			L stored at	t 85+2°C	for 1 h th	on nlacod	at *room
				condition for 24 ± 2					at 100m
							surementa		
				Step	1	2	3	4	5
				Temp.(°C)	20±2	-25±3	20±2	85±2	20±2
	Other with a file sol	D	Less du des stress	lation of the sector of the	A			the Conden	
8	Strength of lead	Pull	Lead wire shou				igure at rig		
			Capacitor should	d not be broken.			itor and a		
							to each lea		
							the capac		har
							diameter	0.5mm),	+11
		Bending	-			p it for 10		ubic stad t	o 5N (2.5N f
		Denuing							
									bent 90° at the
									returned to i
							and bent 9		
0	Vibration	Appeorance	No marked def	oct			te of one l		
9	Vibration resistance	Appearance	No marked defe				ould be firr		ed to the a frequency
	resistance	Capacitance	Within specified						mplitude, wit
		D.F.	Char. B,E : 2.5%						from 10Hz
		1	Char. F : 5.0%	o max.					
		1			to 55Hz and back to 10Hz. Apply for a total of 6 h; 2 h each in 3 mutually perpendicular directions.				
10	Soldorobility of las		Lead wire shou	d bo coldorod					
10	Solderability of lea	ads					•		e dipped into
			direction over 3	oated on the axial			of 25wt% r		
			circumferential						es the depth
			circumierential	direction.			bout 1.5 to	2mm froi	m the root of
					lead wire				
						f solder :		<i>,</i> <u>-</u>	
							Free Sold		g-0.5Cu)
							Eutectic So		
*	"room condition" Te	mperature: 15 to 3	35°C, Relative hur	nidity: 45 to 75%, A	tmospheri	c pressur	e: 86 to 10	06kPa	

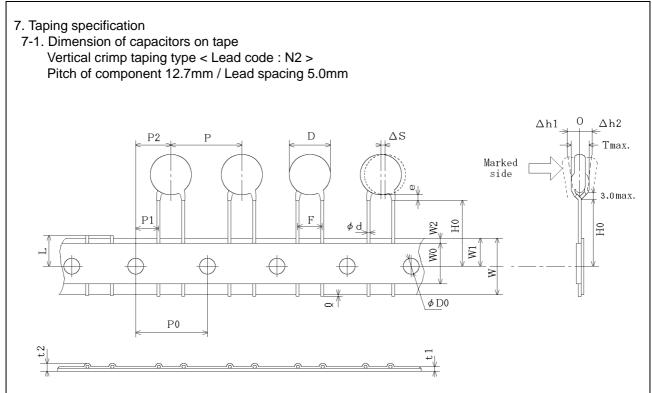
Reference only

			Reference only	
No.	Item		Specification	Test method
11	Soldering effect	Appearance	No marked defect.	The lead wire should be immersed into the melted
	(Non-preheat)	Capacitance	Char. B: Within ± 5%	solder of 350 \pm 10°C (Body of ϕ 5 and under:
		change	Char. E: Within ± 15%	$270\pm5^{\circ}C$) up to about 1.5 to 2.0mm from the
			Char. F: Within ± 20%	main body for 3.5 \pm 0.5 s. (Body of ϕ 5 and under:
		Dielectric	Per item 3.	5±0.5 s.)
		strength		Pre-treatment : Capacitor should be stored at
		(Between		85±2°C for 1 h, then placed at
		lead wires)		* room condition for 24±2 h
				before initial measurements.
				Post-treatment : Capacitor should be stored for
				4 to 24 h at * room condition.
12	Soldering effect	Appearance	No marked defect.	First the capacitor should be stored at
	(On-preheat)	Capacitance	Char. B: Within ± 5%	120+0/-5°C for 60+0/-5 s.
		change	Char. E: Within ± 15%	Then, as in figure, the lead wires should be
			Char. F: Within ± 20%	immersed solder of 260+0/-5°C up to 1.5 to
		Dielectric	Per item 3.	2.0mm from the root of terminal for 7.5+0/-1 s.
		strength		
		(Between		Thermal Capacitor
		lead wires)		
		,		1.5
				Molten
				solder
				Pro troatmont . Consolitor abouild be stored at
				Pre-treatment : Capacitor should be stored at
				85±2°C for 1 h, then placed at * room condition for 24+2 h
				before initial measurements.
				Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.
3	Humidity	Appearance	No marked defect.	Set the capacitor for 500 +24/-0 h at $40\pm2^{\circ}$ C in
9	(Under steady	Capacitance	Char. B : Within ±10%	90 to 95% relative humidity.
	state)	change	Char. E : Within ±20%	Pre-treatment : Capacitor should be stored at
	olalo)	onango	Char. F : Within ±30%	$85\pm2^{\circ}$ C for 1 h, then placed at
		D.F.	Char. B,E : 5.0% max.	* room condition for 24 ± 2 h
		D.F.	Char. F : 7.5% max.	before initial measurements.
		I.R.	1 000MΩ min.	Post-treatment : Capacitor should be stored for 1
		1.1%.		to 2 h at * room condition.
14	Humidity loading	Appearance	No marked defect.	Apply the rated voltage for 500 +24/-0 h at
•	i i annany ioading	Capacitance	Char. B : Within ±10%	$40\pm2^{\circ}$ C in 90 to 95% relative humidity.
		change	Char. E : Within $\pm 10\%$	(Charge/Discharge current≤50mA.)
		Shungo	Char. F : Within $\pm 20\%$ Char. F : Within $\pm 30\%$	Pre-treatment : Capacitor should be stored at
		D.F.	Char. F : Within $\pm 30\%$ Char. B.E : 5.0% max.	85±2°C for 1 h, then placed at
		<i></i> .г.	Char. B,E : 5.0% max. Char. F : 7.5% max.	* room condition for 24±2 h
		1 P		before initial measurements.
		I.R.	500MΩ min.	Post-treatment : Capacitor should be stored at
				$85\pm2^{\circ}$ C for 1 h, then placed at
				* room condition for 24 ± 2 h.
5	Life	Appearance	No marked defect.	Apply a DC voltage of 150% of the rated voltage
~		Capacitance	Char. B : Within ±10%	for 1 000 +48/-0 h at $85\pm2^{\circ}$ C, and relative
		change	Char. E : Within $\pm 20\%$	humidity of 50% max
		change	Char. F : Within $\pm 30\%$	(Charge/Discharge current≤50mA.)
		D.F.	Char. B,E : 4.0% max.	Pre-treatment : Capacitor should be stored at
		U.I.	Char. F : 7.5% max.	$85\pm2^{\circ}$ C for 1 h, then placed at
		I.R.		* room condition for 24 ± 2 h
		1.17.	2000MΩ min.	before initial measurements.
				Post-treatment : Capacitor should be stored at
				$85\pm 2^{\circ}$ C for 1 h, then placed at
				* room condition for 24 ± 2 h.
* "	room condition" Tom	l Derature: 15 to 2	I 5°C, Relative humidity: 45 to 75%, Atm	
	room condition" Temp	beralure: 15 to 3	5 C, Relative numicity: 45 to 75%, Atm	iospheric pressure. 86 to TU6KPa

Reference only

	No. 16	Item						
Immersion cycle Capacitance change Char. B : Within ±10% Char. F : Within ±20% Char. F : Within ±30% 5 temperature cycles, then consecutively to 2 immersion cycles. D.F. Char. B,E : 4.0% max. Char. F : 7.5% max. - I.R. 2 000MΩ min. 2 Room Temp. 3 min Dielectric strength (Between lead wires) Per item 3. - - Step Temperature(°C) Time 3 min - Cycle time: 5 cycle clean - - Dielectric strength (Between lead wires) Per item 3. - - Cycle time: 5 cycle clean - - - Cycle time: 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water 2 0±3 15 min Salt water						Test m	ethod	
change Char. E : Within ±20% Char. F : Within ±30% 2 immersion cycles. <temperature (°c)<="" td=""> Time D.F. Char. B,E : 4.0% max. Char. F : 7.5% max. Step Temperature(°C) Time 1 -25±3 30 min 2 Room Temp. 3 min 2 Room Temp. 3 min 3 +85±3 30 min 4 Room Temp. 3 min 2 cycle time : 5 cycle (Between lead wires) Per item 3. Step Temperature(°C) Time Immersion 2 0±3 15 min water 2 0±3 15 min water 2 0±3 15 min Salt water Cycle time : 2 cycle Cycle time : 2 cycle Cycle time : 2 cycle Operation of cycles</temperature>		Temperature and			The ca	pacitor should be s	subjected to	0
Char. F : Within ±30%		Immersion cycle					n consecut	tively to
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$			change		2 imme	ersion cycles.		
$\frac{1}{1} + \frac{1}{2} + \frac{1}{2} + \frac{1}{2} + \frac{1}{3} + \frac{1}$				Char. F : Within ±30%	-	-		
I.R. 2000MΩ min. Dielectric strength (Between lead wires) Per item 3. I.R. 2000MΩ min. Question Per item 3. I.R. Cycle time : 5 cycle Step Temperature(°C) Step Temperature(°C) I +65+5/-0 I +65+5/-0 I Salt water Question Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.			D.F.	Char. B,E : 4.0% max.			- /	
Dielectric strength (Between lead wires) Per item 3. 3 +85±3 30 min 4 Room Temp. 3 min Cycle time : 5 cycle Cycle time : 5 cycle Step Temperature(°C) Time Immersion water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.				Char. F : 7.5% max.			30 m	nin
Dielectric strength (Between lead wires) Per item 3. Image: Strength (Between lead wires) Per item 3. Image: Strength (Between lead wires) Per item 3. Image: Strength (Between lead wires) Per item 3. Image: Strength Step Temperature(°C) Image: Step Step Imag			I.R.	2000MΩ min.		Room Temp.		
strength (Between lead wires) 4 Room Temp. 3 min Cycle time : 5 cycle Step Temperature(°C) Time Immersion water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.			Dielectric			+85±3		nin
(Between lead wires) (Between lead wires) Cycle time : 5 cycle Step Temperature(°C) Time Immersion water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.					4	Room Temp.	3 mi	in
lead wires) Step Temperature(°C) Time Immersion water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.			(Between				Cycle	e time : 5 cycle
Step Temperature(°C) Time water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.			lead wires)		<imme< td=""><td>rsion cycle></td><td>,</td><td>,</td></imme<>	rsion cycle>	,	,
Step Temperature(°C) Time water 1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.								Immersion
1 +65+5/-0 15 min Clean water 2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.					Step	Temperature(°C)	Time	
2 0±3 15 min Salt water Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.					1	+65+5/-0	15 min	Clean
Cycle time : 2 cycle Pre-treatment : Capacitor should be stored at 85±2°C for 1 h, then placed at * room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 4 to 24 h at * room condition.					2	0±3	15 min	Salt
	* "r(oom condition" Temp	perature: 15 to 3	5°C, Relative humidity: 45 to 75%, Atr	Post-tr	85±2°C * room o before eatment : Capacit 4 to 24 l	or should b for 1 h, the condition for initial mea or should b h at * room	e time : 2 cycle be stored at en placed at or 24 ± 2 h asurements. be stored for

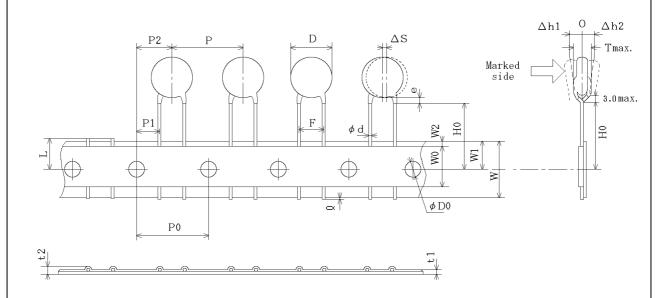




Unit : mm

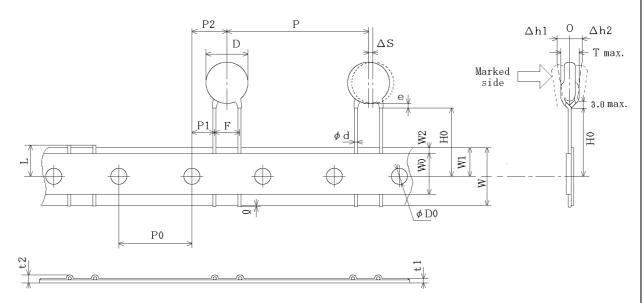
Item	Code	Dimensions	Remarks
Pitch of component	Р	12.7±1.0	
Pitch of sprocket hole	P0	12.7±0.3	
Lead spacing	F	0.8 5.0±0.2	
Length from hole center to component center	P2	6.35±1.3	
Length from hole center to lead	P1	3.85±0.7	Deviation of progress direction
Body diameter	D	Please refer to [P	art number list].
Deviation along tape, left or right	ΔS	0±1.0	They include deviation by lead bend .
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom planes	HO	$18.0\pm^{2.0}_{0}$	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	1.0	
Deviation across tape, rear	∆h2	1.0 max.	
Portion to cut in case of defect	L	11.0± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	Up to the end of c	rimp
Body thickness	Т	Please refer to [P	art number list].

Vertical crimp taping type < Lead code : N3 > Pitch of component 15.0mm / Lead spacing 7.5mm



	·		Unit : mm
Item	Code	Dimensions	Remarks
Pitch of component	Р	15.0±2.0	
Pitch of sprocket hole	P0	15.0±0.3	
Lead spacing	F	7.5±1.0	
Length from hole center to component center	P2	7.5±1.5	
Length from hole center to lead	P1	3.75±1.0	Deviation of progress direction
Body diameter	D	Please refer to [Part number list].
Deviation along tape, left or right	ΔS	0±2.0	They include deviation by lead bend .
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom planes	HO	$18.0\pm_{0}^{2.0}$	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	0.0 mov	
Deviation across tape, rear	∆h2	2.0 max.	
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	Up to the end of	crimp
Body thickness	Т	Please refer to [Part number list].

Vertical crimp taping type < Lead code : N7 > Pitch of component 30.0mm /Lead spacing 7.5mm



Unit : mm

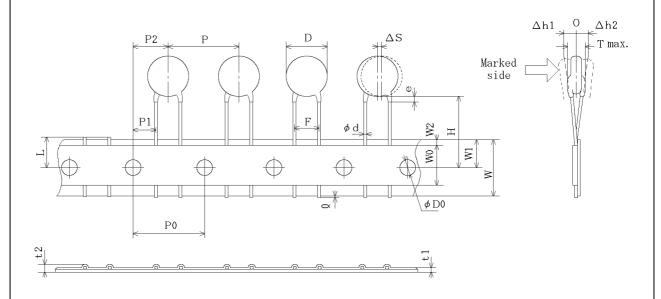
Item	Code	Dimensions	Remarks
Pitch of component	Р	30.0±2.0	
Pitch of sprocket hole	P0	15.0±0.3	
Lead spacing	F	7.5±1.0	
Length from hole center to component center	P2	7.5±1.5	
Length from hole center to lead	P1	3.75±1.0	Deviation of progress direction
Body diameter	D	Please refer to [Part number list].
Deviation along tape, left or right	ΔS	0±2.0	They include deviation by lead bend.
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom planes	HO	$18.0\pm^{2.0}_{0}$	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	0.0	
Deviation across tape, rear	∆h2	2.0 max.	
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	Up to the end of	crimp
Body thickness	Т	Please refer to [Part number list].

Straight taping type < Lead code: P2 > Pitch of component 12.7mm / Lead spacing 5.0mm 0 $\Delta h2$ $\Delta h1$ D ΔS Р2 Р _T max. \rightarrow Marked side Ρ1 F ø d W2 Ξ W0 ΓW \oplus \oplus \oplus ¢ D0 \sim Р0 t 2 ŝ ____ ______ _____ <u></u> -@

Unit : mm

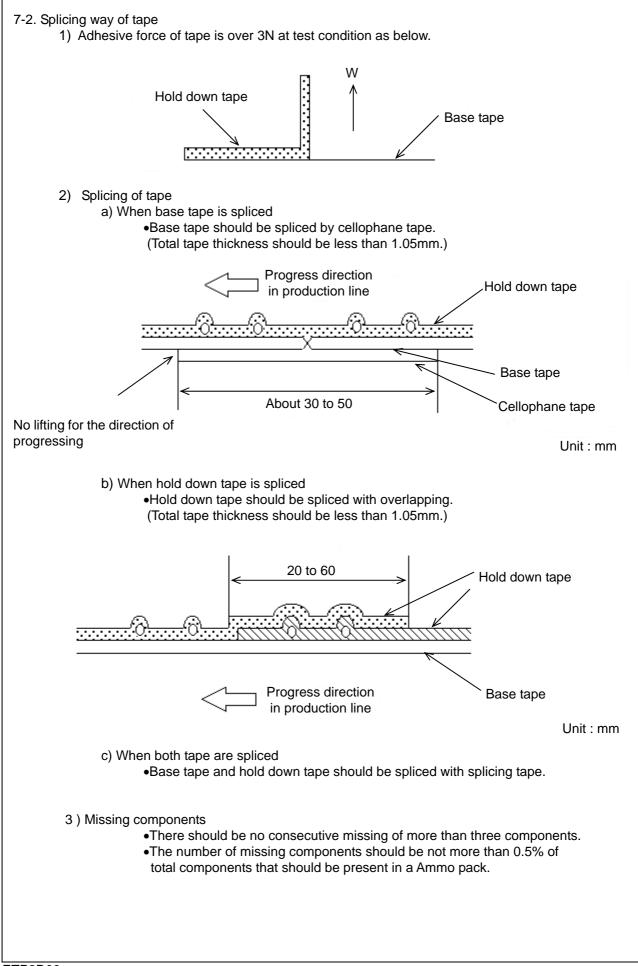
	-		Unit : mm
Item	Code	Dimensions	Remarks
Pitch of component	Р	12.7±1.0	
Pitch of sprocket hole	P0	12.7±0.3	
Lead spacing	F	$5.0\pm^{0.8}_{0.2}$	
Length from hole center to component center	P2	6.35±1.3	Deviation of meaning disaction
Length from hole center to lead	P1	3.85±0.7	Deviation of progress direction
Body diameter	D	Please refer to [F	art number list].
Deviation along tape, left or right	ΔS	0±1.0	They include deviation by lead bend .
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom	н	20.0± ^{1.5}	
planes		20.0±1.0	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	They include hold down tone thickness
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	1.0 max.	
Deviation across tape, rear	∆h2		
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	3.0 max.	
Body thickness	Т	Please refer to [F	Part number list].

Straight taping type < Lead code : P3 > Pitch of component 15.0mm / Lead spacing 7.5mm



Unit : mm

			Unit . Init
ltem	Code	Dimensions	Remarks
Pitch of component	Р	15.0±2.0	
Pitch of sprocket hole	P0	15.0±0.3	
Lead spacing	F	7.5±1.0	
Length from hole center to component center	P2	7.5±1.5	
Length from hole center to lead	P1	3.75±1.0	Deviation of progress direction
Body diameter	D	Please refer to [Part number list].
Deviation along tape, left or right	ΔS	0±2.0	They include deviation by lead bend .
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom planes	н	$20.0\pm^{1.5}_{1.0}$	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	0.0	
Deviation across tape, rear	∆h2	2.0 max.	
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	3.0 max.	
Body thickness	Т	Please refer to [Part number list].



EU RoHS

This products of the following crresponds to EU RoHS.

RoHS

maximum concentration values tolerated by weight in homogeneous materials

- •1000 ppm maximum Lead
- •1000 ppm maximum Mercury
- •100 ppm maximum Cadmium
- •1000 ppm maximum Hexavalent chromium
- •1000 ppm maximum Polybrominated biphenyls (PBB)
- •1000 ppm maximum Polybrominated diphenyl ethers (PBDE)

Mouser Electronics

Authorized Distributor

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Murata:

DEBE33F102ZC3E	B DEBE33D222ZA2E	B DEBB33D471KN2/	A DEBE33D102ZA2	B DEBB33F221KR5A
DEBE33F222ZA3B	DEBB33D471KA2B	DEBB33F471KA3B	DEBE33D103ZECB	DEBE33D103ZA3B
DEBB33F152KA3B	DEBB33D152KA2B	DEBB33F681KA3B	DEBB33D681KA2B	DEBB33F102KA3B
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